

## CLAIMS

- 1/ An electronic assembly comprising at least a first integrated electronic module, the first module including at least one interconnection means for optical connection  
5 to a printed circuit card or to a second electronic module, the assembly including a soleplate and heat removal means for removing heat from said module to the soleplate, and wherein the soleplate is independent of the interconnection means of the first module.
- 10 2/ An assembly according to claim 1, wherein the interconnection means includes an optical fiber.
- 15 3/ An assembly according to claim 2, wherein the optical fiber is included in a printed circuit card, and wherein a first end of the fiber is mounted in register with an optical contact of the first module by means of balls bonded to the module and disposed with precision relative to metal areas of the printed circuit card, the end of  
20 the optical fiber preferably including an etched lens.
- 4/ An assembly according to claim 1, wherein the interconnection means includes a flexible printed circuit.
- 25 5/ An assembly according to claim 1, wherein the interconnection means includes a printed circuit card portion connected to the first module and a second printed circuit card portion connected to the second module, the two cards being interconnected by a second inter-  
30 connection means.
- 6/ An assembly according to claim 5, wherein the two  
35 connection means is constituted by tracks interconnecting the two card portions.

7/ An assembly according to claim 5, wherein the second interconnection means is a flexible printed circuit.

5 8/ An assembly according to claim 1, wherein the interconnection means comprise a contact matrix, the contact matrix being mounted, for example, between the module and the printed circuit card.

10 9/ An assembly according to claim 1, wherein the heat removal means comprise a first segment and a second segment, the first segment connecting the specialist integrated circuit to a first face of the module, this first face being distinct from a second face making contact between the module and the soleplate, and the  
15 second segment connecting said second face to the soleplate.

20 10/ An assembly according to claim 9, wherein the first segment comprises a heat conductive channel.

11/ An assembly according to claim 9, wherein the second segment comprises a closed heat pipe containing a fluid, preferably water and/or alcohol.

25 12/ An assembly according to claim 11, wherein the heat pipe is a long cylindrical tube having a fluted inside wall.